

SEMICONDUCTOR

# **PN3569**

# NPN General Purpose Amplifier

• This device is designed for use at general purpose amplifiers and switches requiring collecor currents to 300mA.



1. Emitter 2. Base 3. Collector

## Absolute Maximum Ratings\* T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	80	V
V <sub>EBO</sub>	Emitter-Base Voltage	5.0	V
I <sub>C</sub>	Collector Current - Continuous	500	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	- 55 ~ 150	°C

\* These ratings are limiting values above whitch the serviceability of any semiconductor device may be impaird.

#### NOTES:

These ratings are based on a maximum junction temperature of 150 degrees C.
These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

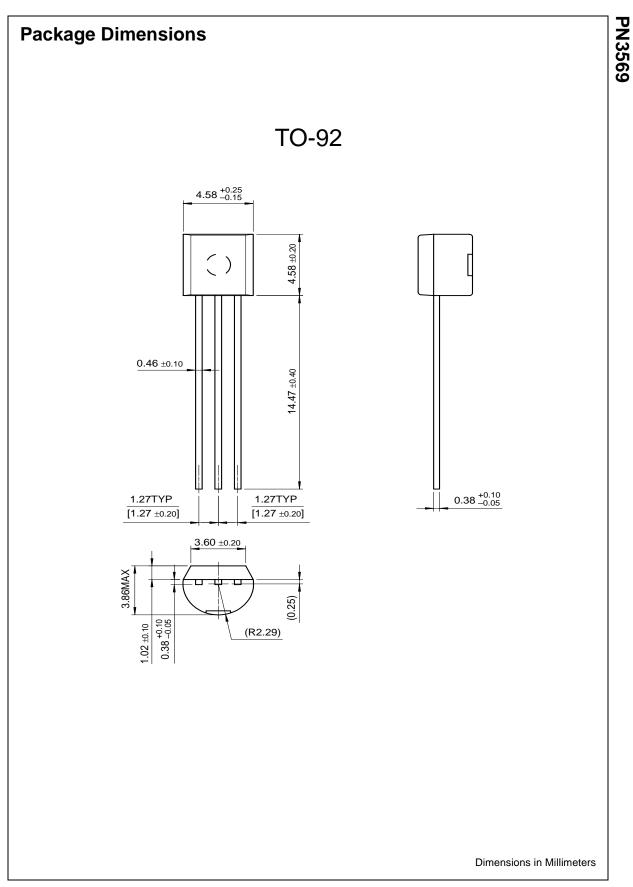
### Electrical Characteristics T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Characte	eristics				
V <sub>(BR)CEO</sub>	Collector-Emitter Sustaining Voltage *	$I_{\rm C} = 30\mu A, I_{\rm B} = 0$	40		V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_{C} = 100 \mu A, I_{E} = 0$	80		
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_{\rm E} = 10\mu A, I_{\rm C} = 0$	5.0		V
I <sub>CBO</sub>	Collector Cutoff Current	$V_{CB} = 40V, I_E = 0$		50	nA
I <sub>EBO</sub>	Emitter Cut-off Current	$V_{EB} = 4.0 V, I_{C} = 0$		25	nA
On Characte	eristics				
h <sub>FE</sub>	DC Current Gain	$V_{CE} = 1V, I_{C} = 150mA$ $V_{CE} = 1V, I_{C} = 30mA$	100 100	300	
V <sub>CE</sub> (sat)	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA		0.25	V
V <sub>BE</sub> (on)	Base-Emitter On Voltage	I <sub>C</sub> = 150mA, V <sub>CE</sub> = 1V		1.1	V
Small Signa	I Characteristics	· · · · · · · · · · · · · · · · · · ·		•	
h <sub>fe</sub>	Small Signal current Gain	I <sub>C</sub> = 50mA, V <sub>CE</sub> = 10V, f = 10MHz	3.0	30	
Pulse Test: Pulse	Width ≤ 300µs, Duty Cycle ≤ 2.0%			•	

### Thermal Characteristics Ta=25°C unless otherwise noted

Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	625	mW
2	Derate above 25°C	5.0	mW/°C
R <sub>θJC</sub>	Thermal Resistance, Junction to Case	83.3	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	200	°C/W

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CROSSVOLT™	GlobalOptoisolator™	MICROWIRE™	QT Optoelectronics <sup>™</sup>	TINYOPTO™
DOME™	GTO™	MSX™	Quiet Series™	TruTranslation™
EcoSPARK™	HiSeC™	MSXPro™	RapidConfigure™	UHC™
E <sup>2</sup> CMOS™	I²C™	OCX™	RapidConnect™	UltraFET <sup>®</sup>
EnSigna™	ImpliedDisconnect™	OCXPro™	SILENT SWITCHER <sup>®</sup>	VCX™
FACT™	ISOPLANAR™	OPTOLOGIC®	SMART START™	
Across the board	. Around the world.™	OPTOPLANAR™	SPM™	
The Power France	hise™	PACMAN™	Stealth™	
Programmable A	ctive Droop™	POP™	SuperSOT™-3	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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